



Customer Information Notification

2016030171

Issue Date: 29-Mar-2016
Effective Date: 27-Jun-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

LPC408x/7x data sheet updates for dynamic external memory interface timing.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Electrical spec./Test coverage

LPC408x/7x data sheet update to Rev. 3.4.

Information Notification

The data sheet for the LPC408X/7X has been updated to Rev. 3.4.

Tables 16 through 18 have been updated with corrected formulas to calculate timing values.

- Updated Table 16 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 00".
- Updated Table 17 "Dynamic characteristics: Dynamic external memory interface, read strategy bits (RD bits) = 01".
- Updated Table 18 "Dynamic characteristics: Dynamic external memory interface programmable clock delays (CMDDLY, FBCLKDLY, CLKOUT0DLY and CLKOUT1DLY)".
- Updated Figure 22 "Dynamic external memory interface signal timing".

See data sheet Tables and Revision History for details.

The revised data sheet is available on the NXP website.

There is no change to the product

Why do we issue this Information Notification

For clarification of data sheet parameters.

Identification of Affected Products

Product identification does not change

Impact

Although no changes have been made to the product, customers should evaluate their applications if an external memory interface is used to interface SDRAM.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind
Position Senior Quality Engineer
e-mail address tim.camenzind@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[| Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.